

Package : VCSP85H2

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1. Structure and materials

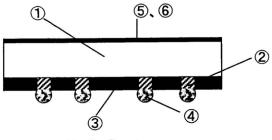


Fig. 1 Structure

No.	Item	Materials
1	Die	Silicon
2	Cu Post	Cu
3	Encapsulation	Epoxy Resin
4	Ext. terminal	Sn-3Ag-0.5Cu Solder
5	Encapsulation	Polyamide-imide Resin
6	Marking	Laser Marking

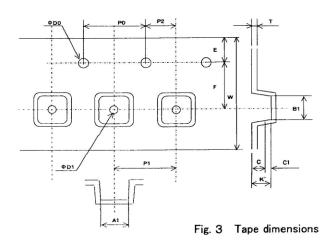
Dehydrated weight : 0.01g

2. Tape and Reel information

2. 1. Packing specification

Таре	Embossed carrier tape	
Quantity	3,000pcs/Reel	
Direction of feed	E2 (See Fig. 2)	

- 2. 2. Tape and Reel specification
- 2. 2. 1. Tape and reel dimensions (See the table on page 2/4)



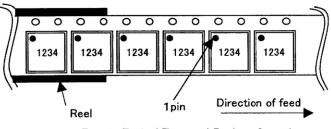


Fig. 2 Typical Tape and Reel configuration

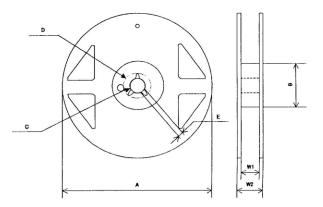


Fig. 4 Reel dimensions

(Tape dimensions)

A1	B1	С	C1	DO	D1	E	F	Κ'	P0	P1	P2	Т	W
3.01	3.01	(0.85)	(0.25)	Φ1.5	Φ1.0	1.75	3.5	1.1	4.0	4.0	2.0	0.3	8.0
±0.1	±0.1			+0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.05	±0.3

(Reel	dimensions)

Α	В	С	D	E	W1	W2
Φ180		13.0 ±0.2				

- 2. 3. Leader and Trailer
- 2. 3. 1. Leader

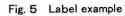
No component pockets are 40 pockets or more.

2. 3. 2. Trailer

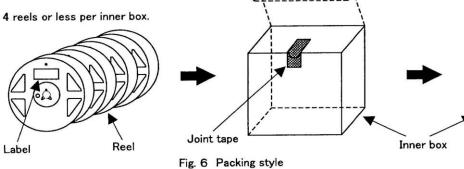
No component pockets are 10 pockets or more. Tape is free from reel.

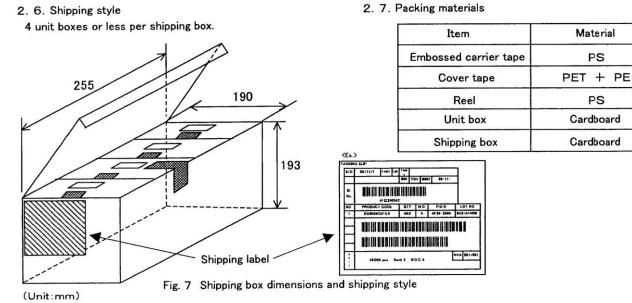
2. 4. Label for Reel and Box





2. 5. Packing style





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Material

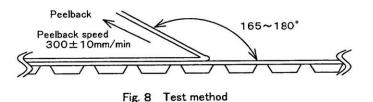
PS

PS

Cardboard Cardboard

- 2.8. Others
- 2. 8. 1. Peelback strength

Cover tape peelback strength is $0.2 \sim 0.7$ N.



2. 8. 2. Dropouts

(1) No consecutive dropouts.

(2) A maximun 0.1% of specified number of products in each packing may be missing.

3. Storage conditions

3. 1. Storage environment

Recommended storage conditions are as follows :

	9900 95000 95000 C
—Temperature	: 5∼30°C

-Humidity	: 40~70% RH

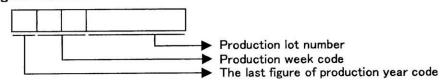
3. 2. Storage period

- Specified storage period : 1 year

3. 3. Specified storage period until soldering

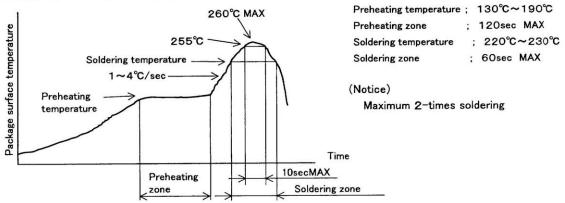
This package dose not require additional drying treatment as long as the moisture condition at the mounting process is within our recommended mounting condition.

4. Marking lot number



5. Soldering conditions

5. 1. Recommended temperature profile for reflow

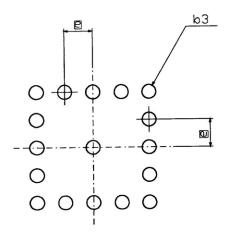


5. 2. About mounting with Sn-Pb solder paste.

Mounting with Sn-Pb solder paste is not recommended because it has a possibility of reducing reliability to connect with Sn-3.0Ag-0.5Cu solder balls.

- 5. 3. The wave soldering method is not supported.
- 5. 4. Partical heat supply method (by soldering iron) is not supported.

6. Footprint dimensions (Optimize footprint dimensions to the board design and soldering condition)



Symbol	Reference Value
e	0.50
b3	0.25

(Unit:mm)

7. Regarding the underfill material

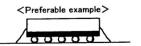
There are some cases that the underfill material is applied as purpose to reinforce the soldered junction of the package. Since the mount reliability depends on the resin material or coating condition, it may deteriorate on the contrary. Therefore, it is necessary to evaluate it sufficiently for its application.

In term of the coating condition, it is preferable that there is an enough material beyond the each four sides of a packeage.

<Non preferable example>

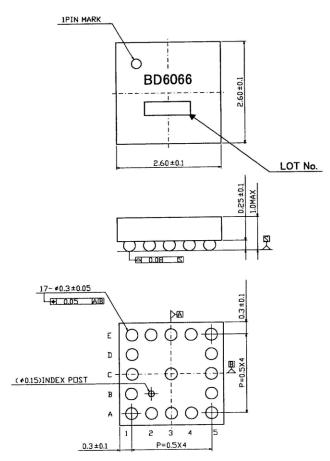
00000

(There is little Underfill resin at one or two sides.)



(There is a Underfill resin evenly at each four sides.)

8. External dimentions



(Unit:mm)

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